

REMARKS

By this Amendment, claims 1 and 4 are amended and claims 11-13 are added.

Accordingly, claims 1, 4 and 11-13 are pending in this application. Reconsideration of the application is respectfully solicited.

Applicant gratefully acknowledges the courtesies extended to Applicant's representative at the personal interview conducted March 10, 2004. The substance of the interview is incorporated into the following remarks, which constitute Applicant's record of the interview.

As discussed during the personal interview, support for the newly added and amended claims can be found in the specification, for example, on page 9, paragraph [0055] and page 13, paragraph [0084].

The Office Action rejects claims 1 and 4 under 35 U.S.C. §102(e) over Sato (U.S. Patent 5,985,064). This rejection is respectfully traversed.

Applicant submits that Sato does not disclose "a pressing chip held in the compression bonding head by the holding means for forming a concave area of a predetermined size in an insulating adhesive layer," as recited in claim 1. Claim 1 thus recites a pressing chip in addition to the semiconductor device.

Sato discloses a compression bonding apparatus wherein "a chip 1 is held by suction or vacuum on a lower surface of a nozzle 3 which is provided at the lower side of the nozzle holding portion 2. The chip 1 has bumps 1a formed on a lower surface thereof, see Fig. 2, and the bumps 1a are compression bonded to the electrodes of the circuit surface of a substrate or circuit board." (See col. 2, lines 61-67). Therefore, Sato discloses only a single chip which is the semiconductor device, rather than a pressing chip.

Therefore, as agreed to during the personal interview, Sato does not disclose each and every feature of claim 1. Claim 4 depends from claim 1, and is patentable for at least the

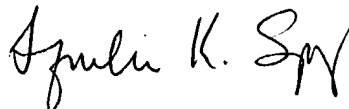
reasons set forth above with respect to claim 1, as well as for the additional features it recites. Therefore, Applicant respectfully requests that the rejection of claims 1 and 4 under §102(e) be withdrawn.

Claims 11-13 depend from claim 1, and are patentable for at least the reasons set forth above with respect to claim 1, as well as for the additional features they recite.

In view of the foregoing, it is respectfully submitted that this application is in condition for allowance. Favorable reconsideration and prompt allowance of claims 1, 4 and 11-13 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in even better condition for allowance, the Examiner is invited to contact the undersigned at the telephone number set forth below.

Respectfully submitted,



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